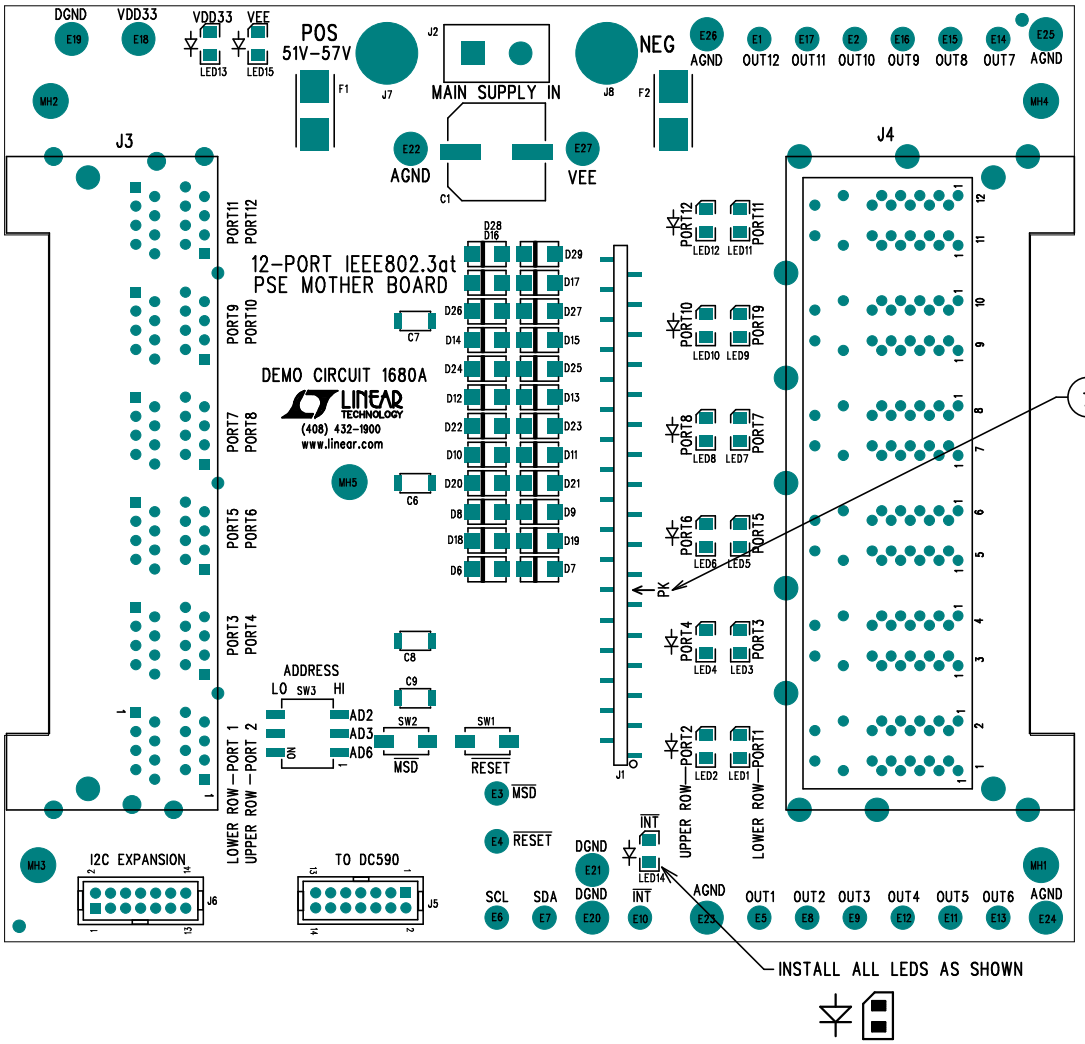
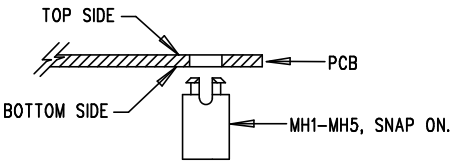
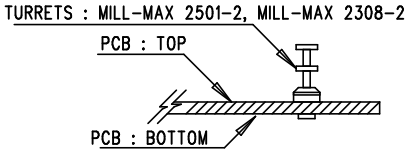


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
–	3	PRODUCTION	DILIAN R.	2-24-11

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL PK PIN ON J1 PIN 12 AS SHOWN ON DRAWING: 1680A3-ASSY-J1.PDF
8. INSTALL 5 STANDOFFS AT 5 LOCATIONS AS SHOWN BELOW:





APPROVALS	
PCB DES.	JW
APP ENG.	DILIAN R.
SCALE = NONE	

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TITLE: TOP ASSEMBLY DRAWING
12-PORT IEEE802.3at
PSE MOTHER BOARD

SIZE	IC NO.	REV.
N/A	DEMO CIRCUIT 1680A	3

FILENAME: 1680A-3.PCB SHT 1 OF 2